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(54) Title: METHOD FOR PICKING UP SEMICONDUCTOR CHIPS FROM A WAFER TABLE AND MOUNTING THE REMOVED SEMICONDUCTOR CHIPS ON A SUBSTRATE

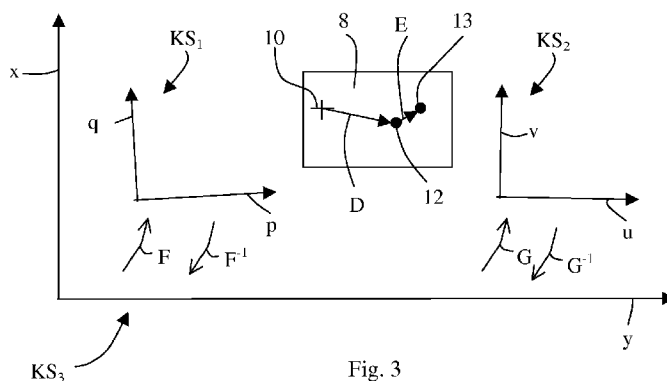


Fig. 3

(57) Abstract: The invention relates to a method for picking up semiconductor chips (2) from a wafer table (1) and mounting them on a substrate (4) by means of a pick-and-place system (5). The position and orientation of the semiconductor chip (2) to be mounted next are determined by means of a first camera (6) and made available in the form of positional data relating to a first system of coordinates (KS1). The position and orientation of the substrate place on which the semiconductor chip (2) will be mounted are determined by means of a second camera (7) and made available in the form of positional data relating to a second system of coordinates (KS2). The conversion of coordinates of the first and second systems of coordinates into coordinates of motion of the pick-and-place system (5) occurs by means of two fixed mapping functions (F, G) and two changeable correction vectors (K1, K2). The correction vectors (K1, K2) are readjusted on the occurrence of a predetermined event.